



BSI Standards Publication

Integrated circuits – Three dimensional integrated circuits

Part 2: Alignment of stacked dies having fine pitch interconnect

National foreword

This British Standard is the UK implementation of IEC 63011-2:2018.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Published by BSI Standards Limited 2019

ISBN 978 0 580 97375 8

ICS 31.200

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This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 January 2019.

Amendments/corrigenda issued since publication

Date	Text affected
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IEC 63011-2

Edition 1.0 2018-11

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Integrated circuits – Three dimensional integrated circuits –
Part 2: Alignment of stacked dies having fine pitch interconnect**

**Circuits intégrés – Circuits intégrés tridimensionnels –
Partie 2: Alignement de puces empilées à petits pas d'interconnexion**

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INTERNATIONALE

ICS 31.200

ISBN 978-2-8322-6291-7

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